503449360 08/24/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
HARUHIKO SAKAI	08/02/2009

RECEIVING PARTY DATA

Name:	SANYO ELECTRIC CO., LTD.
Street Address:	2-5-5, KEIHANHONDORI
City:	MORIGUCHI-SHI, OSAKA
State/Country:	JAPAN
Postal Code:	570-8677
Name:	SANYO SEMICONDUCTOR CO., LTD.
Name: Street Address:	SANYO SEMICONDUCTOR CO., LTD. 1-1-1, SAKATA, OIZUMI-MACHI
	,
Street Address:	1-1-1, SAKATA, OIZUMI-MACHI

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	12904851	

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	200802637D01
NAME OF SUBMITTER:	KELLY A. NELSON
SIGNATURE:	/Kelly A. Nelson/
DATE SIGNED:	08/24/2015

PATENT 503449360 REEL: 036404 FRAME: 0703

Total Attachments: 2

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PATENT REEL: 036404 FRAME: 0704

MORRISON & FOERSTER LLP

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the undersigned hereby assigns, transfers and sets over to:

SANYO Electric Co., Ltd. 2-5-5, Keihanhondori Moriguchi-Shi, Osaka 570-8677 Japan

And

SANYO Semiconductor Co., Ltd. 1-1-1, Sakata, Oizumi-Machi, Ora-Gun Gunma 370-0596 Japan

(hereinafter designated as the "ASSIGNEES"), its successors and assigns, the entire right, title, and interest for the United States in the invention, and all applications for patent and any Letters Patent which may be granted therefore, including said application, and all United States Letters Patent which may be granted thereof, and all divisions, reissues, continuations and extensions thereof, the said interest being the entire ownership of said Letters Patent when granted to be held by said ASSIGNEES, its successors, assigns or their legal representatives, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been and enjoyed by Assignor(s) if this assignment had not been made, the application being known by the title:

SEMICONDUCTOR DEVICE AND SEMICONDUCTOR MODULE, MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND LEAD FRAME

Attorney Docket No: 492322040800

for which the undersigned has/have executed an application for patent in the United States of America on the same day herewith. Where this instrument is not filed concurrently with the application, the following identifying information may be added after execution:

Filing Date:

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prosecution of said any continuing, cor reissue application	The undersigned her truments which may be a above-named application tinuation-in-part, substitute or in any amendments, at the title thereto to the	necessary, lawion or in the pre itute, divisional extension of in	ful and proper in the paration and prosecul, renewal, reexamina	ition of ation oi

The undersigned agrees to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property of similar agreements.

1

Docket No. 492322940892ENT

Serial No:

- 3. The undersigned agrees to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the ASSIGNEES.
- 4. The undersigned hereby authorizes and requests the Commissioner of Patents in the United States to issue any and all Letters Patent resulting from said application or any division or divisions or continuing applications thereof to the said ASSIGNEES.
- 5. The undersigned hereby grants to the firm of Morrison & Foerster LLP the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREBY, executed by the undersigned on the date opposite the undersigned name.

Date

Aug. 2, 2009

Name: Haruhiko SAKAI